

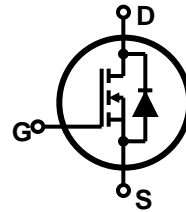
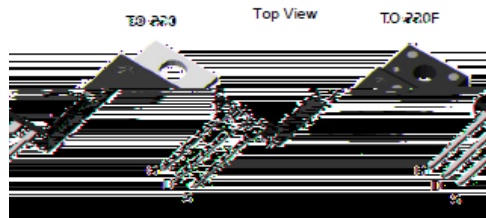
## Features

- Low gate charge
- 100% avalanche tested
- Improved dv/dt capability
- RoHS compliant
- Halogen free package
- JEDEC Qualification
- Fast reverse recovery

$$V_{DSS} = 550 \text{ V @ } T_{jmax}$$

$$I_D = 4 \text{ A}$$

$$R_{DS(ON)} = 1.85 \text{ (max) @ } V_{GS} = 10 \text{ V}$$



Device	Package	Marking	Remark
TMP5N50SG / TMPF5N50SG	TO-220 / TO-220F	TMP5N50SG / TMPF5N50SG	Halogen Free

## Absolute Maximum Ratings

Parameter	Symbol	TMP5N50SG	TMPF5N50SG	Unit	
Drain-Source Voltage	$V_{DSS}$	500		V	
Gate-Source Voltage	$V_{GS}$	±30		V	
Continuous Drain Current	$I_D$	$T_C = 25 \text{ }^\circ\text{C}$	4 *	A	
		$T_C = 100 \text{ }^\circ\text{C}$	2.8 *	A	
Pulsed Drain Current (Note 1)	$I_{DM}$	16	16*	A	
Single Pulse Avalanche Energy (Note 2)	$E_{AS}$	240		mJ	
Repetitive Avalanche Current (Note 1)	$I_{AR}$	4		A	
Repetitive Avalanche Energy (Note 1)	$E_{AR}$	9.25		mJ	
Power Dissipation	$P_D$	$T_C = 25 \text{ }^\circ\text{C}$	92.5	32	W
		Derate above 25 $^\circ\text{C}$	0.74	0.25	W/ $^\circ\text{C}$
Peak Diode Recovery dv/dt (Note 3)	dv/dt	4.5		V/ns	
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~150		$^\circ\text{C}$	
Maximum lead temperature for soldering purposes,	$T_L$	300		$^\circ\text{C}$	

\* Limited only by maximum junction temperature

## Thermal Characteristics

Parameter	Symbol	TMP5N50SG	TMPF5N50SG	Unit
Maximum Thermal resistance, Junction-to-Case	$R_{JC}$	1.35	3.9	$^\circ\text{C}/\text{W}$
Maximum Thermal resistance, Junction-to-Ambient	$R_{JA}$	62.5	62.5	$^\circ\text{C}/\text{W}$

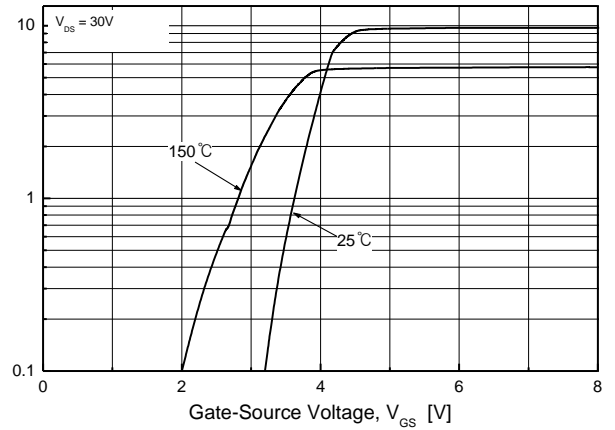
**Electrical Characteristics** :  $T_C=25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test condition	Min	Typ	Max	Units
<b>OFF</b>						
Drain-Source Breakdown Voltage	$BV_{DS}$	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	500	--	--	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 500\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	$\mu\text{A}$
		$V_{DS} = 400\text{ V}, T_C = 125^\circ\text{C}$	--	--	10	$\mu\text{A}$
Forward Gate-Source Leakage Current	$I_{GSSF}$	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
Reverse Gate-Source Leakage Current	$I_{GSSR}$	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA
<b>ON</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	1.5	--	3.5	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 2\text{ A}$	--	1.5	1.85	
Forward Transconductance <sup>(Note 4)</sup>	$g_{FS}$	$V_{DS} = 30\text{ V}, I_D = 2\text{ A}$	$\angle$	8	$\angle$	S

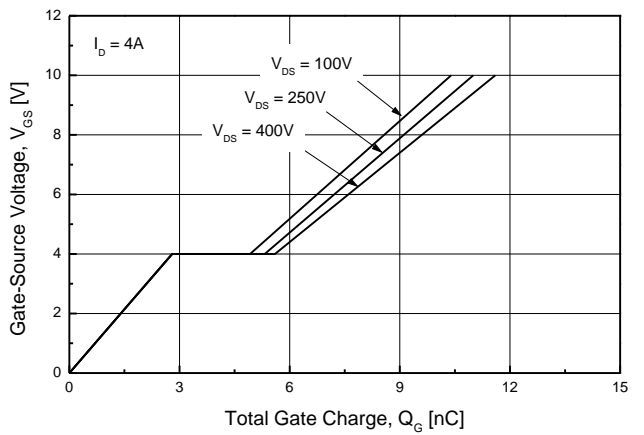
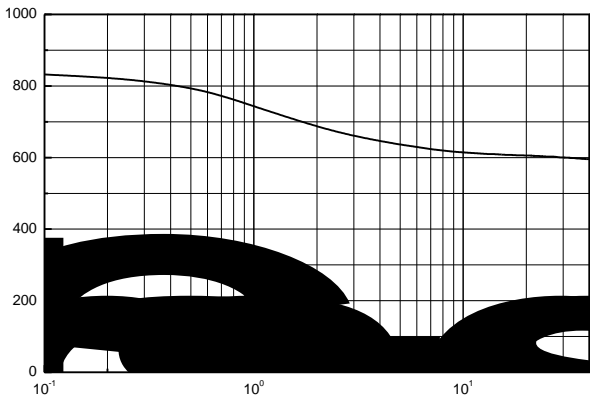
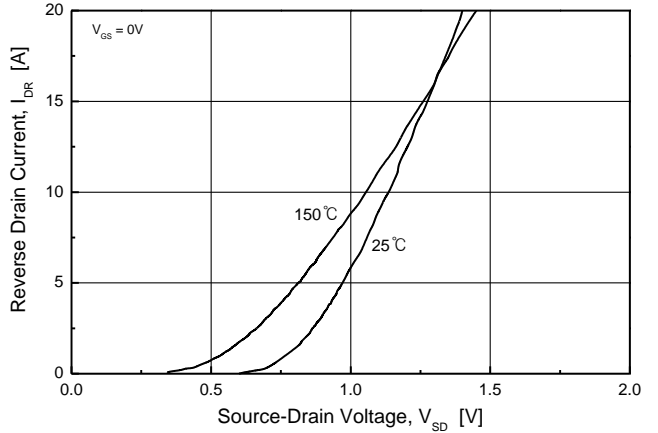
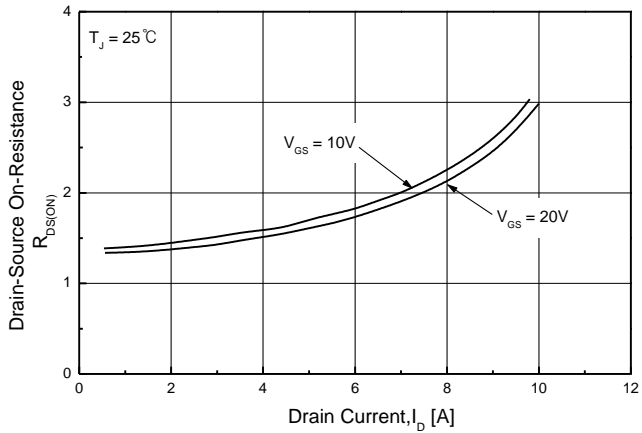
**DYNAMIC**

InputCateCID 81/L--						

- Note :
- Repeated rating : Pulse width limited by safe operating area
  - $L=27\text{mH}, I_{AS} = 4\text{A}, V_{DD} = 50\text{V}, R_G = 25\ \Omega$ , Starting  $T_J = 25^\circ\text{C}$
  - $I_{SD}$   $\mu\text{s}, V_{DD}$   $\mu\text{s}, V_{DS}$ , Starting  $T_J = 25^\circ\text{C}$
  - 
  - Essentially Independent of Operating Temperature Typical Characteristics

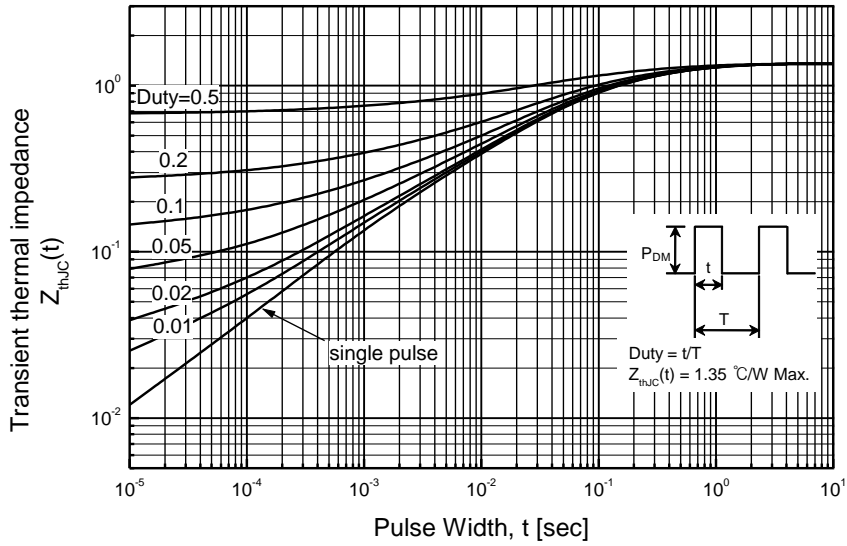


DS



TMP5N50SG

TMP5N50SG



TMPF5N50SG

